

PATENT APPLICATION

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Susumu KANZAKI, et al.

Appln. No.: 10/087,810

Group Art Unit: 1713

Confirmation No.: 2976

Examiner: PENDING

Filed: March 05, 2002

For: POLYPROPYLENE-BASED RESIN COMPOSITION, PROCESS FOR PRODUCING

THE SAME, AND INJECTION MOLDED ARTICLE

## PRELIMINARY AMENDMENT

Commissioner for Patents Washington, D.C. 20231

Sir:

Prior to examination, kindly amend the above-identified application as follows:

## IN THE SPECIFICATION:

Page 24, line 14

The content of 1-butene contained in the above-mentioned ethylene-1-butene random copolymer rubber is preferably from 15 to 35% by weight, more preferably from 17 to 33% by weight.

**CLAIMS:** 

Page 78,

9. The polypropylene-based resin composition according to Claim 1, wherein the polypropylene-based resin composition has a melt flow rate (MFR) measured according to JIS-K-6758 of 5 to 150 g/10 minutes.